



Storage and Shelf Life of Efinix Products

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Introduction

Efinix® FPGAs are generally packed in trays or tape-and-reel packaging. MSL 3 devices are shipped in a sealed moisture barrier bag (MBB) with a desiccant and a humidity indicator card (HIC). MSL 1 devices are shipped in a sealed MBB without desiccant and HIC.

For more information on the packages, solder reflow guidelines, and PCB guidelines, refer to:

- [Trion® Packaging User Guide](#)
- [Titanium Packaging User Guide](#)

Shelf Life

For an unopened bag stored in a non-condensing atmospheric environment of $< 40^{\circ}\text{C}$ and $< 90\%$ relative humidity (RH), the shelf life is:

- MSL 3 devices—24 months from the bag seal date.
- MSL 1 devices—Unlimited.

Opening the MBB indicates the beginning of the floor life countdown.

- Floor life for MSL 3 devices is 168 hours (7 days) under environmental conditions of $\leq 30^{\circ}\text{C}$ and $\leq 60\%$ RH.
- MSL 1 devices have unlimited floor life under environmental conditions of $\leq 30^{\circ}\text{C}$ and $\leq 85\%$ RH.

If the floor life has expired or other conditions have occurred to indicate excess moisture exposure, you can re-bake MSL 3 devices per the condition set in IPC/JEDEC J-STD-033 prior to use. This re-baking drives out residual moisture so that the device can be stored again or soldered without any risk of being damaged.

Revision History

Table 1: Revision History

Date	Version	Description
May 2022	1.0	Initial release.